



UNISONIC TECHNOLOGIES CO., LTD

產 品 變 更 通 知

PRODUCT CHANGE NOTIFICATION

PCN No.	IC-PPCN-120101	Issue Date	Jan-17-2012
TITLE	Notification of process change from Conductive epoxy to Soft-solder in partial of SOT-89 devices		Page 1 of 2

變更主旨(TITLE):

爲了提升產品品質，SOT-89 將部分產品粘晶製程由導電膠轉成Solder(芯片大小 > 1.0*1.0mm)。
 Transfer die attachment process from Conductive epoxy to Soft-Solder for promoting quality in partial of SOT-89 devices (chip size > 1.0*1.0mm).

變更類別(CHANGE TYPE):

- Design Process Raw Material Manufacturing Site
 Testing Packing/Shipping/Labeling Other _____

變更說明(DESCRIPTION OF CHANGE):

	Original	New
Process type	Dispensing	Soft-Solder
Die attach material	Conductive epoxy	Pb93.5-Sn5-Ag1.5

品質驗證(VERIFICATION/QUALIFICATION):

Solder製程已通過可靠性測試，且不影響原承認書保證之特性。驗證資料如下。

Reliability test were qualified for soft-solder process and qualification data are as bellowed,

1. Assembly report.
2. Reliability report.

生效日期(COMPLETE DATE):

2012/02/01

影響範圍(APPLICABLE PRODUCTS):

1. SOT-89 部分產品，清單如附件一
 Partial of SOT-89 devices, detail effected devices are as attachment 1.
2. UTC保留可出貨導電膠製程產品的權力至庫存消化完畢
 UTC reserves the right to ship original conductive epoxy product until the inventory has been depleted.



產 品 變 更 通 知

PRODUCT CHANGE NOTIFICATION

PCN No.	IC-PPCN-111106	Issue Date	Dec-5-2011
TITLE	Notification of process change from Eutectic to Soft-solder in partial of SOT-89 devices		Page 2 of 2

客戶回簽(CUSTOMER RESPONSE):

請使用以下的確認通知回覆或以電子郵件同意認可或告知需要補充的資訊。如UTC於15日以內未收到確認通知，我們將視同貴司同意此變更。

Please use the acknowledgement below or E-Mail to grant approval or request additional information. If UTC does not receive acknowledgement within 15 days of this notice it will be assumed that this change is acceptable.

Approved Rejected Other _____

Customer Signature: _____

友順對此變更所引起之不便表達致歉，如果對本變更有任何問題，請與我們的業務代表或經銷商聯絡。

We apologize for any inconvenience causing from this change, If you have any questions concerning this change, please contact your local sales or UTC's sales representative.

附件一 (Attachment 1)

影響產品清單(Effected devices list)

	成品名稱	規格	製程
	Device	Ordering Number	Process
1	MCR100-6/8	MCR100L-6-x-AB3-R/ MCR100G-6-x-AB3-R MCR100L-8-x-AB3-R/ MCR100G-8-x-AB3-R	Epoxy --> Solder
2	2SC5569	2SC5569L-AB3-R 2SC5569G-AB3-R	Epoxy --> Solder
3	2SD1060	2SD1060L-x-AB3-R/2SD1060G-x-AB3-R	Epoxy --> Solder
4	2SD1624	2SD1624L-x-AB3-R/2SD1624G-x-AB3-R	Epoxy --> Solder
5	UT06P03	UT06P03L-AB3-R UT06P03G-AB3-R	Epoxy --> Solder
6	UT9435	UT9435L-AB3-R/ UT9435G-AB3-R	Epoxy --> Solder
7	UTM2054	UTM2054L-AB3-R/ UTM2054G-AB3-R	Epoxy --> Solder
8	2SA2016	2SA2016L-AB3-R 2SA2016G-AB3-R	Epoxy --> Solder
9	2SC3647	2SC3647L-x-AB3-R/2SC3647G-x-AB3-R	Epoxy --> Solder